

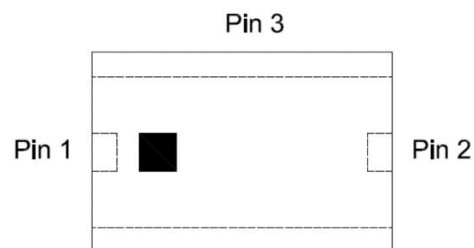
### Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

### Specifications

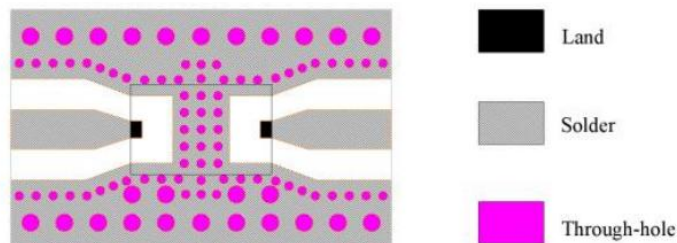
| NO. | Parameter                        | Frequency (MHz) | SPC  |      |
|-----|----------------------------------|-----------------|------|------|
|     |                                  |                 | Min. | Max. |
| 1   | Insertion Loss (dB)              | 2200~3800       |      | 2.0  |
| 2   | Attenuation (dB)                 | 1200            | 20   |      |
|     |                                  | 4400            | 6    |      |
| 3   | VSWR                             | 2200~3800       |      | 1.5  |
| 4   | In/Output Impedance ( $\Omega$ ) |                 | 50   |      |

### Construction



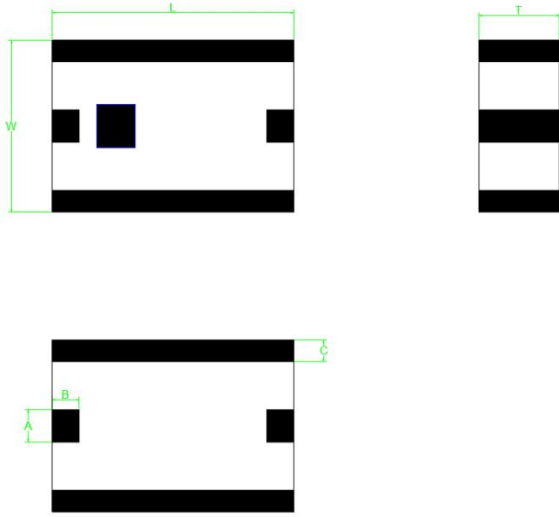
| PIN | Connection  |
|-----|-------------|
| 1   | Input Port  |
| 2   | Output Port |
| 3   | GND         |
| 4   | GND         |

### Mounting Considerations

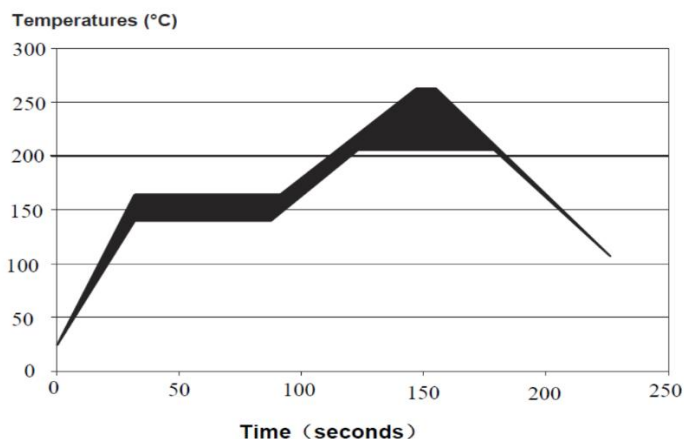


Unit: mm  
Line width to be designed to match 50  $\Omega$  characteristic impedance, depending on PCB material and thickness

### Dimensions

| Figure                                                                             | Symbol | Dimension (mm) |
|------------------------------------------------------------------------------------|--------|----------------|
|  | L      | 4.50±0.20      |
|                                                                                    | W      | 3.20±0.20      |
|                                                                                    | T      | 1.50±0.20      |
|                                                                                    | A      | 0.60±0.10      |
|                                                                                    | B      | 0.50±0.10      |
|                                                                                    | C      | 0.40±0.10      |

### Solder Reflow Standard Conditioning



### Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) \*

Baking : Unnecessary

\* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.